

SEMICONDUCTOR CIRCUIT WITH MULTIPLE CONTACT SIZES

ABSTRACT OF THE DISCLOSURE

A semiconductor circuit comprising a semiconductor die and a package substrate. In one embodiment, a first plurality of conductive bumps serves as a portion of a conductive path between contacts on the semiconductor die and contacts on the package substrate. A second plurality of conductive bumps serves as a portion of a conductive path between other contacts on the die and contacts on the package substrate. Each of the bumps in the first plurality of conductive bumps is larger than each of the bumps in the second plurality of conductive bumps. In another embodiment, the average size of the first plurality of conductive bumps may be at least 20% larger (or greater) than the average size of the second plurality of bumps.